

General Description

The MY3407A is the high cell density trench P-CH MOSFET, which provide excellent $R_{DS(ON)}$ and efficiency for most of the small power switching and load switch applications.

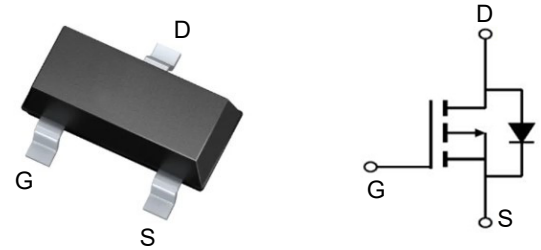


Features

V_{DSS}	-30	V
I_D	-4.2	A
$R_{DS(ON)}$ (at $V_{GS}=4.5V$)	41	m Ω
$R_{DS(ON)}$ (at $V_{GS}=2.5V$)	53	m Ω

Application

- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY3407A	SOT-23	3407	3000

Absolute Maximum Ratings ($T_A=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_A=25^{\circ}C$	Continuous Drain Current	-4.2	A
$I_D@T_A=70^{\circ}C$	Continuous Drain Current	-3.6	A
I_{DM}	Pulsed Drain Current ²	-16	A
$P_D@T_A=25^{\circ}C$	Total Power Dissipation ³	1.5	W
$P_D@T_A=70^{\circ}C$	Total Power Dissipation ³	1.0	W
T_{STG}	Storage Temperature Range	-55 to 150	$^{\circ}C$
T_J	Operating Junction Temperature Range	-55 to 150	$^{\circ}C$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	---	105	$^{\circ}C/W$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹ ($t \leq 10s$)	---	---	$^{\circ}C/W$

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-30	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -30V, V _{GS} = 0V	-	-	-1	μA
Gate-Source Leakage	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
Gate-Source Threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-1	-1.5	-2.5	V
Drain-Source on-State Resistance ³	R _{DS(on)}	V _{GS} = -10V, I _D = -4.1A	-	41	60	mΩ
		V _{GS} = -4.5V, I _D = -3A	-	53	85	
Dynamic Characteristics ⁴						
Input Capacitance	C _{iss}	V _{GS} = 0V , V _{DS} = -15V, f = 1.0MHz	-	530	-	pF
Output Capacitance	C _{oss}		-	70	-	
Reverse Transfer Capacitance	C _{rss}		-	56	-	
Switching Characteristics ⁴						
Total Gate Charge	Q _g	V _{GS} = -10V, V _{DS} = -15V, I _D = -4.1A	-	6.8	-	nC
Gate-Source Charge	Q _{gs}		-	1.0	-	
Gate-Drain Charge	Q _{gd}		-	1.4	-	
Turn-on Delay Time	t _{d(on)}	V _{GS} = -10V, V _{DS} = -15V , R _L = 15Ω,R _{GEN} = 2.5Ω	-	14	-	ns
Rise Time	t _r		-	61	-	
Turn-off Delay time	t _{d(off)}		-	19	-	
Fall Time	t _f		-	10	-	
Source-Drain Body Diode Characteristics						
Diode Forward Voltage ³	V _{SD}	I _S = -4.1A, V _{GS} = 0V	-	-	-1.2	V
Continuous Source Current	I _S		-	-	-4.5	A

Notes:

1. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C.
2. The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper, The value in any given application depends on the user's specific board design.
3. Pulse Test: Pulse width≤300μs, duty cycle≤2%.
4. This value is guaranteed by design hence it is not included in the production test.

Typical Electrical and Thermal Characteristics

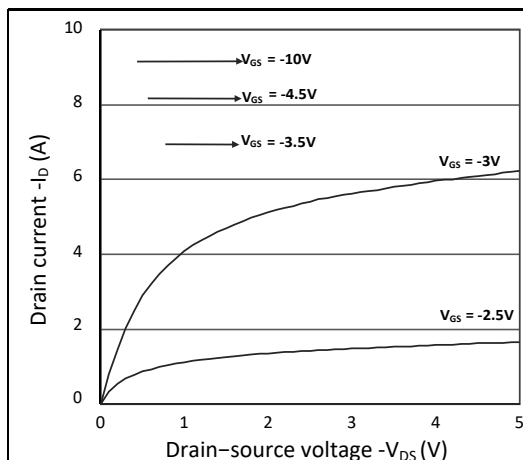


Figure 1. Output Characteristics

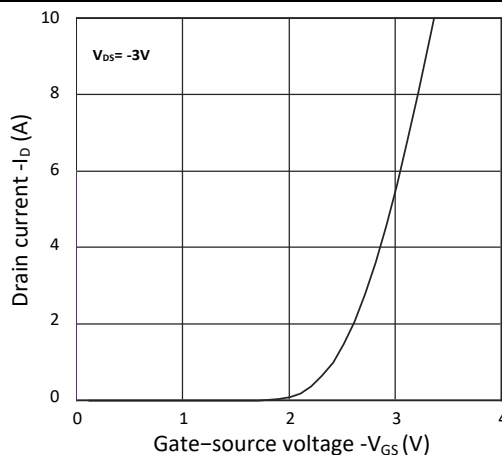


Figure 2. Transfer Characteristics

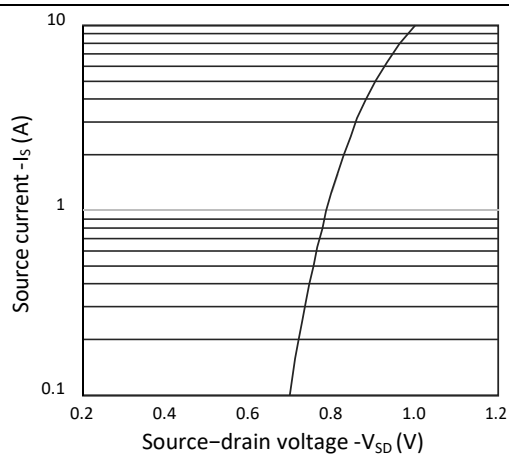


Figure 3. Forward Characteristics of Reverse

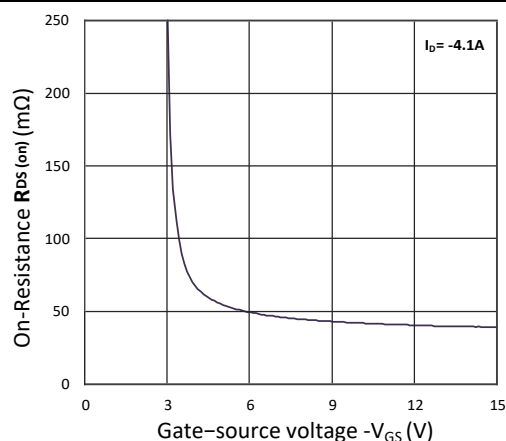


Figure 4. $R_{DS(on)}$ vs. V_{GS}

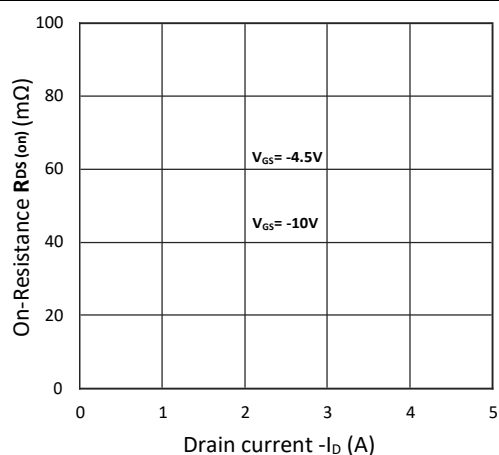


Figure 5. $R_{DS(on)}$ vs. I_D

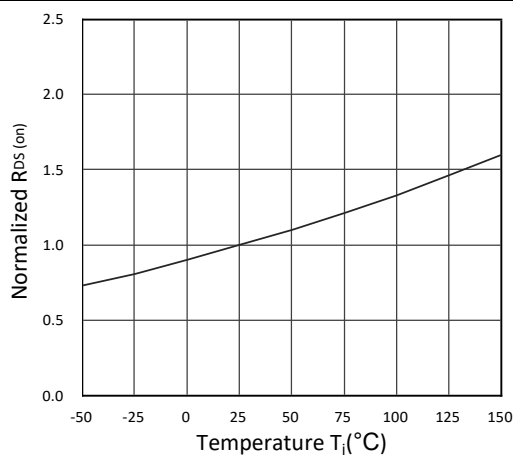


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature

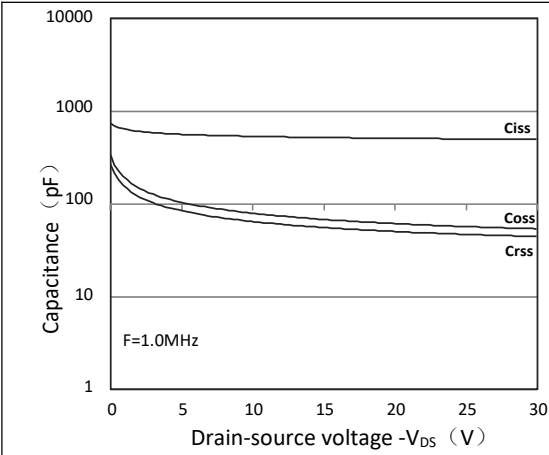


Figure 7. Capacitance Characteristics

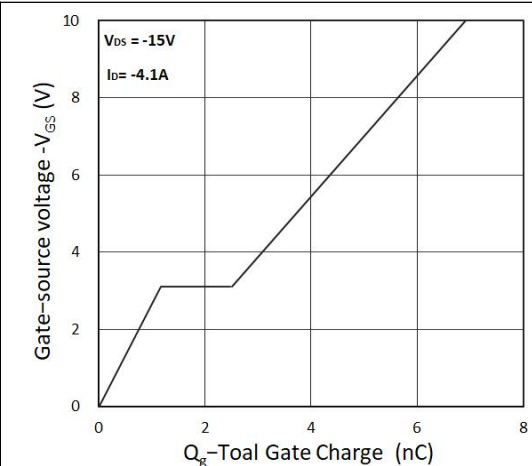
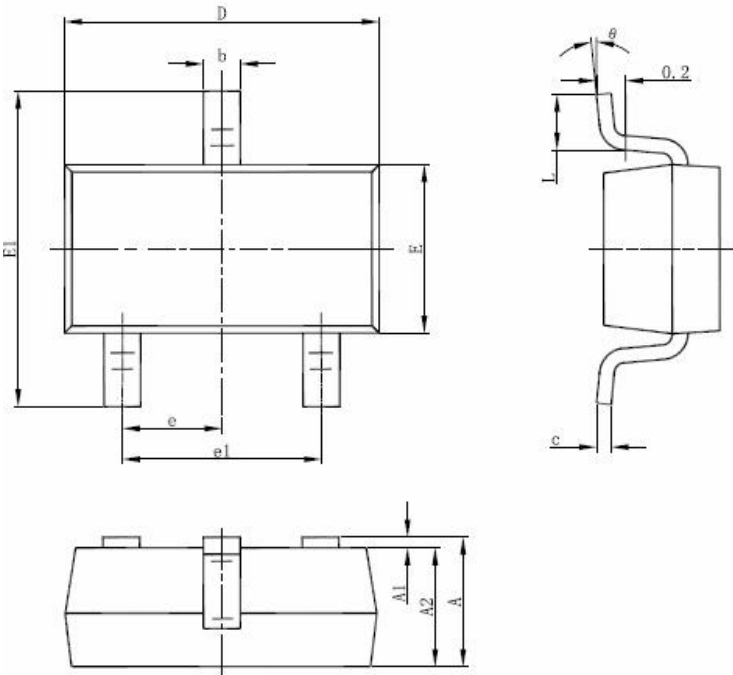


Figure 8. Gate Charge Characteristics

Package Mechanical Data-SOT-23



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°